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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Active
Number of LABs/CLBs	32
Number of Logic Elements/Cells	256
Total RAM Bits	-
Number of I/O	44
Number of Gates	-
Voltage - Supply	2.375V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	64-VFBGA
Supplier Device Package	64-UCBGA (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo2-256hc-4umg64c

Table 1-1. MachXO2™ Family Selection Guide

	XO2-256	XO2-640	XO2-640U ¹	XO2-1200	XO2-1200U ¹	XO2-2000	XO2-2000U ¹	XO2-4000	XO2-7000
LUTs	256	640	640	1280	1280	2112	2112	4320	6864
Distributed RAM (kbytes)	2	5	5	10	10	16	16	34	54
EBR SRAM (kbytes)	0	18	64	64	74	74	92	92	240
Number of EBR SRAM Blocks (9 kbytes/block)	0	2	7	7	8	8	10	10	26
UFM (kbytes)	0	24	64	64	80	80	96	96	256
Device Options:	HC ²	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
	HE ³					Yes	Yes	Yes	Yes
	ZE ⁴	Yes	Yes		Yes	Yes		Yes	Yes
Number of PLLs	0	0	1	1	1	1	2	2	2
Hardened Functions:	I2C	2	2	2	2	2	2	2	2
	SPI	1	1	1	1	1	1	1	1
	Timer/Counter	1	1	1	1	1	1	1	1
Packages					IO				
25-ball WLCSP ⁵ (2.5 mm x 2.5 mm, 0.4 mm)				18					
32 QFN ⁶ (5 mm x 5 mm, 0.5 mm)	21			21					
48 QFN ^{8, 9} (7 mm x 7 mm, 0.5 mm)	40	40							
49-ball WLCSP ⁵ (3.2 mm x 3.2 mm, 0.4 mm)					38				
64-ball ucBGA (4 mm x 4 mm, 0.4 mm)	44								
84 QFN ⁷ (7 mm x 7 mm, 0.5 mm)							68		
100-pin TQFP (14 mm x 14 mm)	55	78		79		79			
132-ball csBGA (8 mm x 8 mm, 0.5 mm)	55	79		104		104		104	
144-pin TQFP (20 mm x 20 mm)			107	107		111		114	114
184-ball csBGA ⁷ (8 mm x 8 mm, 0.5 mm)								150	
256-ball caBGA (14 mm x 14 mm, 0.8 mm)						206		206	206
256-ball ftBGA (17 mm x 17 mm, 1.0 mm)					206	206		206	206
332-ball caBGA (17 mm x 17 mm, 0.8 mm)								274	278
484-ball ftBGA (23 mm x 23 mm, 1.0 mm)							278	278	334

1. Ultra high I/O device.
2. High performance with regulator – VCC = 2.5 V, 3.3 V
3. High performance without regulator – V_{CC} = 1.2 V
4. Low power without regulator – V_{CC} = 1.2 V
5. WLCSP package only available for ZE devices.
6. 32 QFN package only available for HC and ZE devices.
7. 184 csBGA package only available for HE devices.
8. 48-pin QFN information is ‘Advanced’.
9. 48 QFN package only available for HC devices.

The logic blocks, Programmable Functional Unit (PFU) and sysMEM EBR blocks, are arranged in a two-dimensional grid with rows and columns. Each row has either the logic blocks or the EBR blocks. The PIO cells are located at the periphery of the device, arranged in banks. The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PIOs utilize a flexible I/O buffer referred to as a sysIO buffer that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

In the MachXO2 family, the number of sysIO banks varies by device. There are different types of I/O buffers on the different banks. Refer to the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found in MachXO2-640/U and larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT usage.

The MachXO2 registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

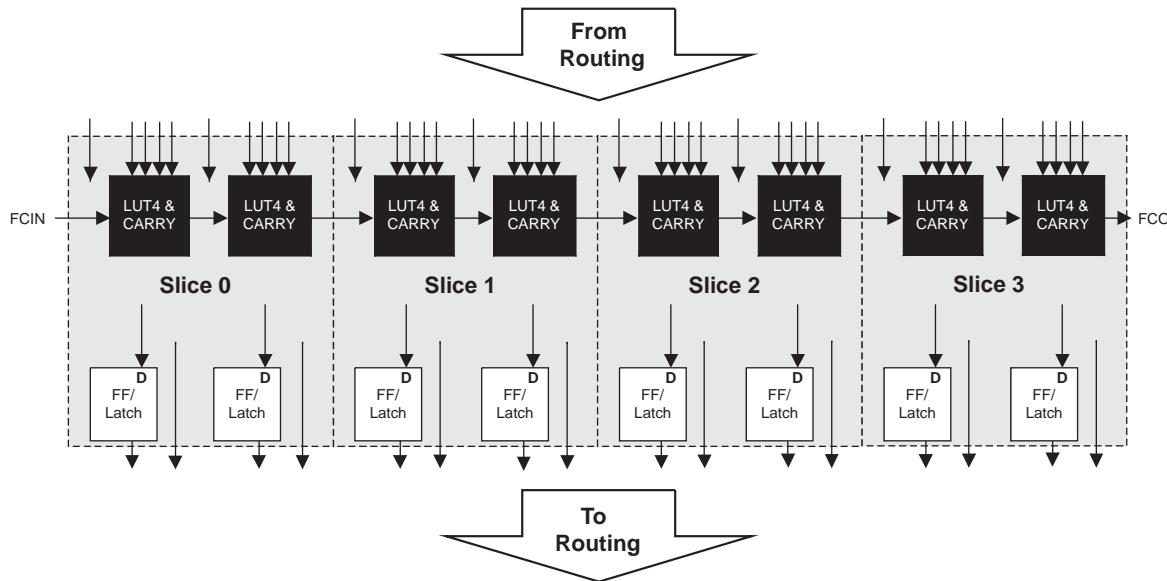
The MachXO2 architecture also provides up to two sysCLOCK Phase Locked Loop (PLL) blocks on MachXO2-640U, MachXO2-1200/U and larger devices. These blocks are located at the ends of the on-chip Flash block. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

MachXO2 devices provide commonly used hardened functions such as SPI controller, I²C controller and timer/counter. MachXO2-640/U and higher density devices also provide User Flash Memory (UFM). These hardened functions and the UFM interface to the core logic and routing through a WISHBONE interface. The UFM can also be accessed through the SPI, I²C and JTAG ports.

Every device in the family has a JTAG port that supports programming and configuration of the device as well as access to the user logic. The MachXO2 devices are available for operation from 3.3 V, 2.5 V and 1.2 V power supplies, providing easy integration into the overall system.

PFU Blocks

The core of the MachXO2 device consists of PFU blocks, which can be programmed to perform logic, arithmetic, distributed RAM and distributed ROM functions. Each PFU block consists of four interconnected slices numbered 0 to 3 as shown in Figure 2-3. Each slice contains two LUTs and two registers. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-3. PFU Block Diagram


Slices

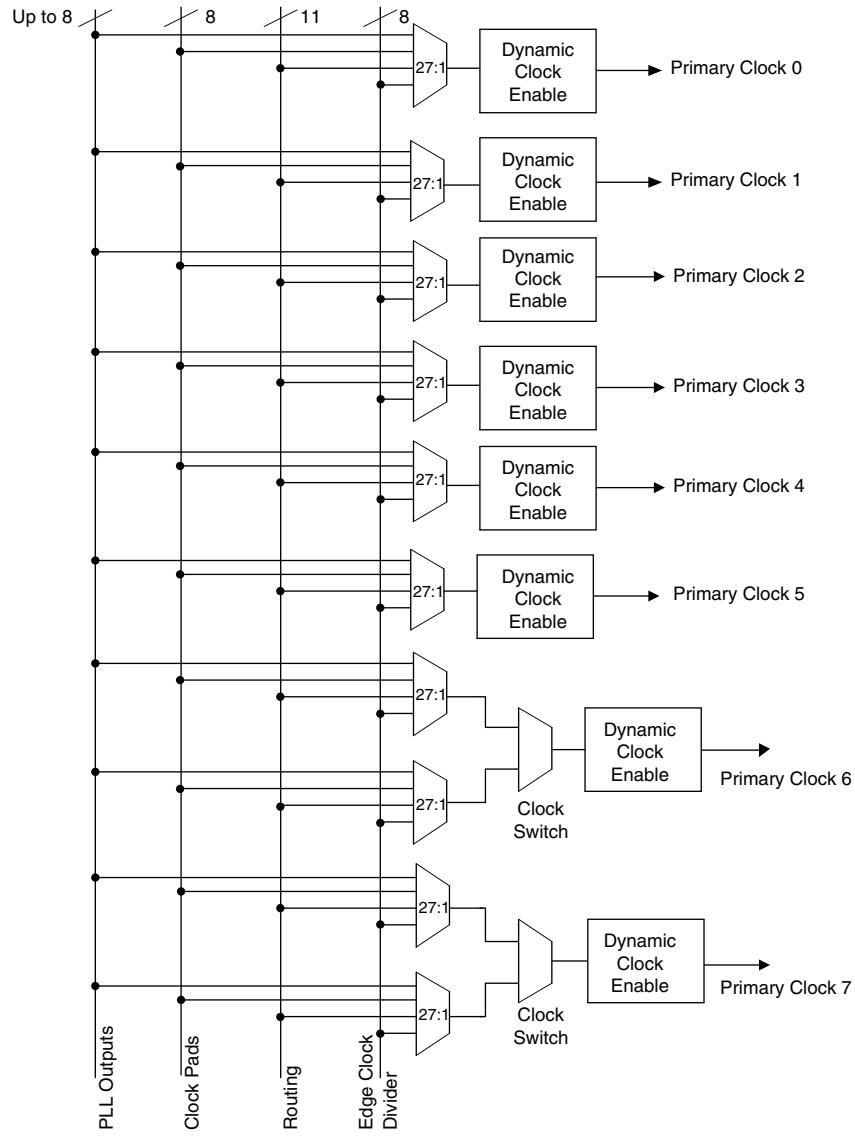
Slices 0-3 contain two LUT4s feeding two registers. Slices 0-2 can be configured as distributed memory. Table 2-1 shows the capability of the slices in PFU blocks along with the operation modes they enable. In addition, each PFU contains logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. The control logic performs set/reset functions (programmable as synchronous/ asynchronous), clock select, chip-select and wider RAM/ROM functions.

Table 2-1. Resources and Modes Available per Slice

Slice	PFU Block	
	Resources	Modes
Slice 0	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM
Slice 1	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM
Slice 2	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM
Slice 3	2 LUT4s and 2 Registers	Logic, Ripple, ROM

Figure 2-4 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge triggered or level sensitive clocks. All slices have 15 inputs from routing and one from the carry-chain (from the adjacent slice or PFU). There are seven outputs: six for routing and one to carry-chain (to the adjacent PFU). Table 2-2 lists the signals associated with Slices 0-3.

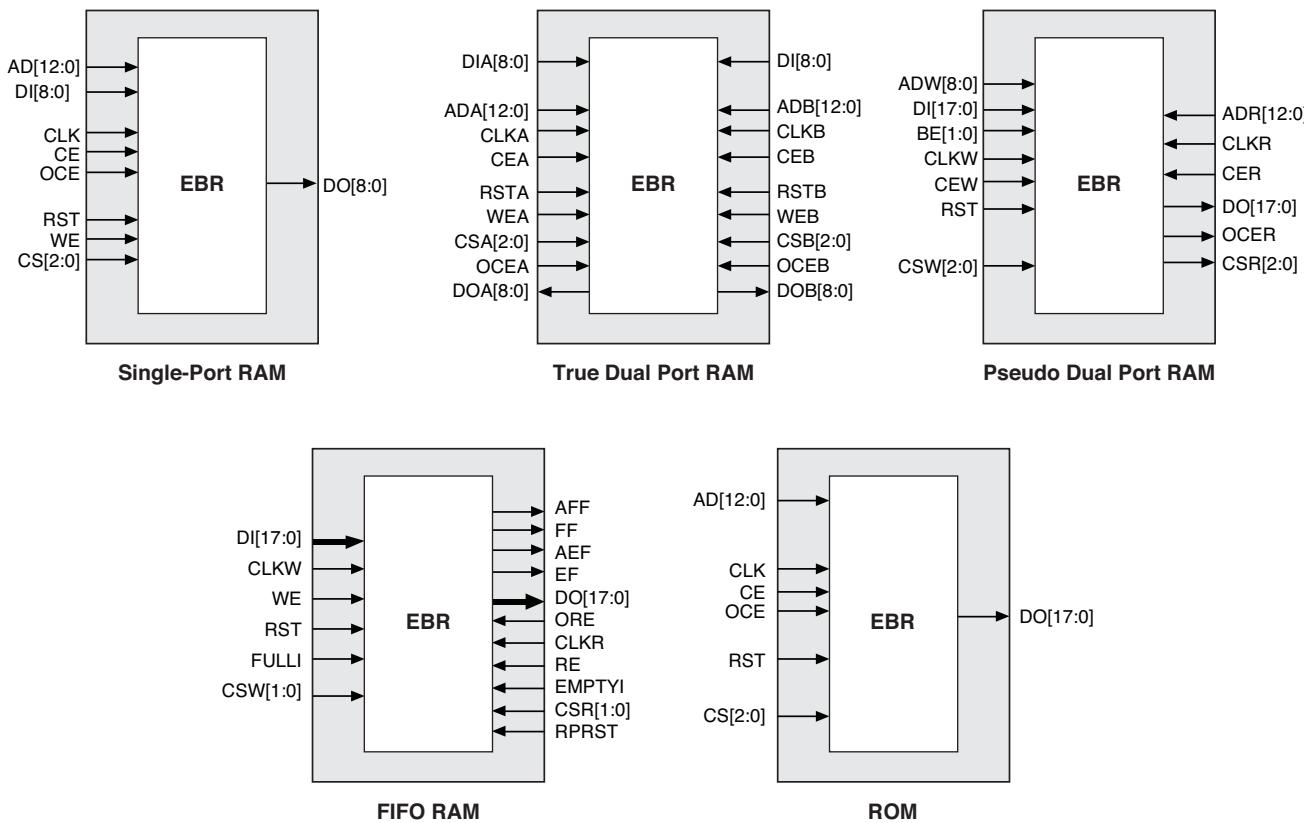
Figure 2-5. Primary Clocks for MachXO2 Devices



Primary clocks for MachXO2-640U, MachXO2-1200/U and larger devices.

Note: MachXO2-640 and smaller devices do not have inputs from the Edge Clock Divider or PLL and fewer routing inputs. These devices have 17:1 muxes instead of 27:1 muxes.

Eight secondary high fanout nets are generated from eight 8:1 muxes as shown in Figure 2-6. One of the eight inputs to the secondary high fanout net input mux comes from dual function clock pins and the remaining seven come from internal routing. The maximum frequency for the secondary clock network is shown in MachXO2 External Switching Characteristics table.

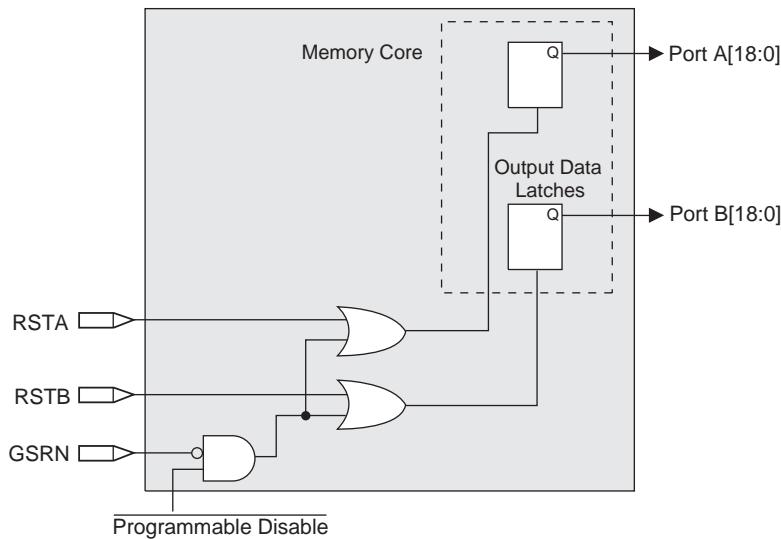
Figure 2-8. sysMEM Memory Primitives

Table 2-6. EBR Signal Descriptions

Port Name	Description	Active State
CLK	Clock	Rising Clock Edge
CE	Clock Enable	Active High
OCE ¹	Output Clock Enable	Active High
RST	Reset	Active High
BE ¹	Byte Enable	Active High
WE	Write Enable	Active High
AD	Address Bus	—
DI	Data In	—
DO	Data Out	—
CS	Chip Select	Active High
AFF	FIFO RAM Almost Full Flag	—
FF	FIFO RAM Full Flag	—
AEF	FIFO RAM Almost Empty Flag	—
EF	FIFO RAM Empty Flag	—
RPRST	FIFO RAM Read Pointer Reset	—

1. Optional signals.

2. For dual port EBR primitives a trailing ‘A’ or ‘B’ in the signal name specifies the EBR port A or port B respectively.
3. For FIFO RAM mode primitive, a trailing ‘R’ or ‘W’ in the signal name specifies the FIFO read port or write port respectively.
4. For FIFO RAM mode primitive FULLI has the same function as CSW(2) and EMPTYI has the same function as CSR(2).
5. In FIFO mode, CLKW is the write port clock, CSW is the write port chip select, CLKR is the read port clock, CSR is the read port chip select, ORE is the output read enable.

Figure 2-9. Memory Core Reset

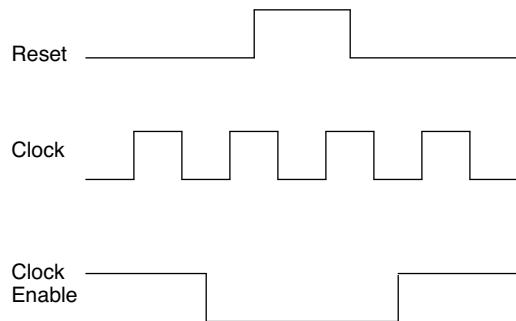


For further information on the sysMEM EBR block, please refer to TN1201, [Memory Usage Guide for MachXO2 Devices](#).

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-10. The GSR input to the EBR is always asynchronous.

Figure 2-10. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device wake up must occur before the release of the device I/Os becoming active.

These instructions apply to all EBR RAM, ROM and FIFO implementations. For the EBR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-10. The reset timing rules apply to the RPReset input versus the RE input and the RST input versus the WE and RE inputs. Both RST and RPReset are always asynchronous EBR inputs. For more details refer to TN1201, [Memory Usage Guide for MachXO2 Devices](#).

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

Static Supply Current – HC/HE Devices^{1, 2, 3, 6}

Symbol	Parameter	Device	Typ. ⁴	Units
I _{CC}	Core Power Supply	LCMxo2-256HC	1.15	mA
		LCMxo2-640HC	1.84	mA
		LCMxo2-640UHC	3.48	mA
		LCMxo2-1200HC	3.49	mA
		LCMxo2-1200UHC	4.80	mA
		LCMxo2-2000HC	4.80	mA
		LCMxo2-2000UHC	8.44	mA
		LCMxo2-4000HC	8.45	mA
		LCMxo2-7000HC	12.87	mA
		LCMxo2-2000HE	1.39	mA
		LCMxo2-4000HE	2.55	mA
		LCMxo2-7000HE	4.06	mA
I _{CCIO}	Bank Power Supply ⁵ V _{CCIO} = 2.5 V	All devices	0	mA

1. For further information on supply current, please refer to TN1198, [Power Estimation and Management for MachXO2 Devices](#).

2. Assumes blank pattern with the following characteristics: all outputs are tri-stated, all inputs are configured as LVCMOS and held at V_{CCIO} or GND, on-chip oscillator is off, on-chip PLL is off.

3. Frequency = 0 MHz.

4. T_J = 25 °C, power supplies at nominal voltage.

5. Does not include pull-up/pull-down.

6. To determine the MachXO2 peak start-up current data, use the Power Calculator tool.

Programming and Erase Flash Supply Current – HC/HE Devices^{1, 2, 3, 4}

Symbol	Parameter	Device	Typ. ⁵	Units
I _{CC}	Core Power Supply	LCMxo2-256HC	14.6	mA
		LCMxo2-640HC	16.1	mA
		LCMxo2-640UHC	18.8	mA
		LCMxo2-1200HC	18.8	mA
		LCMxo2-1200UHC	22.1	mA
		LCMxo2-2000HC	22.1	mA
		LCMxo2-2000UHC	26.8	mA
		LCMxo2-4000HC	26.8	mA
		LCMxo2-7000HC	33.2	mA
		LCMxo2-2000HE	18.3	mA
		LCMxo2-2000UHE	20.4	mA
		LCMxo2-4000HE	20.4	mA
I _{CCIO}	Bank Power Supply ⁶	All devices	0	mA

1. For further information on supply current, please refer to TN1198, [Power Estimation and Management for MachXO2 Devices](#).

2. Assumes all inputs are held at V_{CCIO} or GND and all outputs are tri-stated.

3. Typical user pattern.

4. JTAG programming is at 25 MHz.

5. T_J = 25 °C, power supplies at nominal voltage.

6. Per bank. V_{CCIO} = 2.5 V. Does not include pull-up/pull-down.

Programming and Erase Flash Supply Current – ZE Devices^{1, 2, 3, 4}

Symbol	Parameter	Device	Typ. ⁵	Units
I _{CC}	Core Power Supply	LCMXO2-256ZE	13	mA
		LCMXO2-640ZE	14	mA
		LCMXO2-1200ZE	15	mA
		LCMXO2-2000ZE	17	mA
		LCMXO2-4000ZE	18	mA
		LCMXO2-7000ZE	20	mA
I _{CCIO}	Bank Power Supply ⁶	All devices	0	mA

1. For further information on supply current, please refer to TN1198, [Power Estimation and Management for MachXO2 Devices](#).

2. Assumes all inputs are held at V_{CCIO} or GND and all outputs are tri-stated.

3. Typical user pattern.

4. JTAG programming is at 25 MHz.

5. TJ = 25 °C, power supplies at nominal voltage.

6. Per bank. V_{CCIO} = 2.5 V. Does not include pull-up/pull-down.

Input/Output Standard	V _{IL}		V _{IH}		V _{OL} Max. (V)	V _{OH} Min. (V)	I _{OL} Max. ⁴ (mA)	I _{OH} Max. ⁴ (mA)
	Min. (V) ³	Max. (V)	Min. (V)	Max. (V)				
LVCMOS10R25	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	3.6	0.40	NA Open Drain	16, 12, 8, 4	NA Open Drain

1. MachXO2 devices allow LVCMOS inputs to be placed in I/O banks where V_{CCIO} is different from what is specified in the applicable JEDEC specification. This is referred to as a ratioed input buffer. In a majority of cases this operation follows or exceeds the applicable JEDEC specification. The cases where MachXO2 devices do not meet the relevant JEDEC specification are documented in the table below.
2. MachXO2 devices allow for LVCMOS referenced I/Os which follow applicable JEDEC specifications. For more details about mixed mode operation please refer to please refer to TN1202, [MachXO2 sysIO Usage Guide](#).
3. The dual function I²C pins SCL and SDA are limited to a V_{IL} min of -0.25 V or to -0.3 V with a duration of <10 ns.
4. For electromigration, the average DC current sourced or sunk by I/O pads between two consecutive VCCIO or GND pad connections, or between the last VCCIO or GND in an I/O bank and the end of an I/O bank, as shown in the Logic Signal Connections table (also shown as I/O grouping) shall not exceed a maximum of n * 8 mA. "n" is the number of I/O pads between the two consecutive bank VCCIO or GND connections or between the last VCCIO and GND in a bank and the end of a bank. IO Grouping can be found in the Data Sheet Pin Tables, which can also be generated from the Lattice Diamond software.

Input Standard	V _{CCIO} (V)	V _{IL} Max. (V)
LVCMOS 33	1.5	0.685
LVCMOS 25	1.5	0.687
LVCMOS 18	1.5	0.655

sysIO Differential Electrical Characteristics

The LVDS differential output buffers are available on the top side of MachXO2-640U, MachXO2-1200/U and higher density devices in the MachXO2 PLD family.

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V _{INP} V _{INM}	Input Voltage	V _{CCIO} = 3.3 V	0	—	2.605	V
		V _{CCIO} = 2.5 V	0	—	2.05	V
V _{THD}	Differential Input Threshold		±100	—		mV
V _{CM}	Input Common Mode Voltage	V _{CCIO} = 3.3 V	0.05	—	2.6	V
		V _{CCIO} = 2.5 V	0.05	—	2.0	V
I _{IN}	Input current	Power on	—	—	±10	µA
V _{OH}	Output high voltage for V _{OP} or V _{OM}	R _T = 100 Ohm	—	1.375	—	V
V _{OL}	Output low voltage for V _{OP} or V _{OM}	R _T = 100 Ohm	0.90	1.025	—	V
V _{OD}	Output voltage differential	(V _{OP} - V _{OM}), R _T = 100 Ohm	250	350	450	mV
ΔV _{OD}	Change in V _{OD} between high and low		—	—	50	mV
V _{OS}	Output voltage offset	(V _{OP} + V _{OM})/2, R _T = 100 Ohm	1.125	1.20	1.395	V
ΔV _{OS}	Change in V _{OS} between H and L		—	—	50	mV
I _{OSD}	Output short circuit current	V _{OD} = 0 V driver outputs shorted	—	—	24	mA

LVPECL

The MachXO2 family supports the differential LVPECL standard through emulation. This output standard is emulated using complementary LVCMS outputs in conjunction with resistors across the driver outputs on all the devices. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Differential LVPECL is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

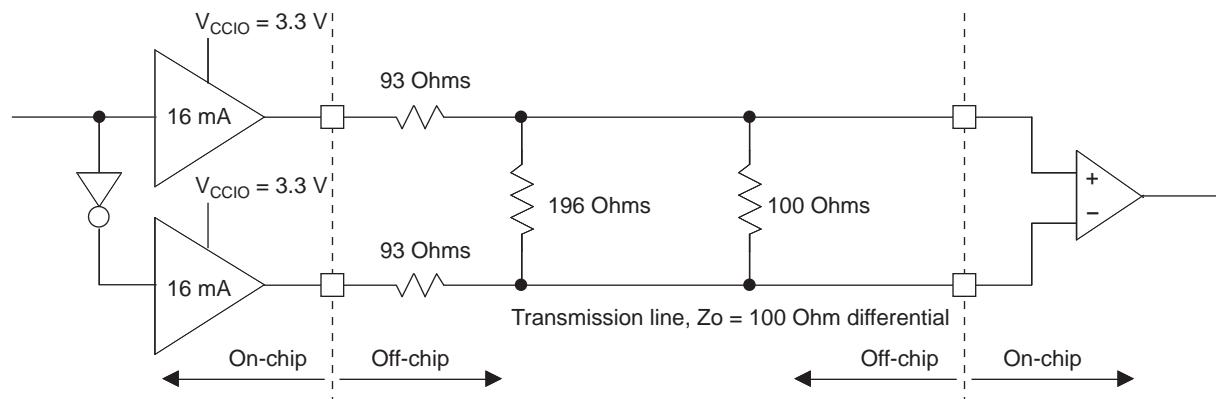


Table 3-3. LVPECL DC Conditions¹

Over Recommended Operating Conditions

Symbol	Description	Nominal	Units
Z_{OUT}	Output impedance	20	Ohms
R_S	Driver series resistor	93	Ohms
R_P	Driver parallel resistor	196	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	2.05	V
V_{OL}	Output low voltage	1.25	V
V_{OD}	Output differential voltage	0.80	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	100.5	Ohms
I_{DC}	DC output current	12.11	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

Maximum sysIO Buffer Performance

I/O Standard	Max. Speed	Units
LVDS25	400	MHz
LVDS25E	150	MHz
RSDS25	150	MHz
RSDS25E	150	MHz
BLVDS25	150	MHz
BLVDS25E	150	MHz
MLVDS25	150	MHz
MLVDS25E	150	MHz
LVPECL33	150	MHz
LVPECL33E	150	MHz
SSTL25_I	150	MHz
SSTL25_II	150	MHz
SSTL25D_I	150	MHz
SSTL25D_II	150	MHz
SSTL18_I	150	MHz
SSTL18_II	150	MHz
SSTL18D_I	150	MHz
SSTL18D_II	150	MHz
HSTL18_I	150	MHz
HSTL18_II	150	MHz
HSTL18D_I	150	MHz
HSTL18D_II	150	MHz
PCI33	134	MHz
LVTTL33	150	MHz
LVTTL33D	150	MHz
LVCMOS33	150	MHz
LVCMOS33D	150	MHz
LVCMOS25	150	MHz
LVCMOS25D	150	MHz
LVCMOS25R33	150	MHz
LVCMOS18	150	MHz
LVCMOS18D	150	MHz
LVCMOS18R33	150	MHz
LVCMOS18R25	150	MHz
LVCMOS15	150	MHz
LVCMOS15D	150	MHz
LVCMOS15R33	150	MHz
LVCMOS15R25	150	MHz
LVCMOS12	91	MHz
LVCMOS12D	91	MHz

Parameter	Description	Device	-6		-5		-4		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{HPLL}	Clock to Data Hold – PIO Input Register	MachXO2-1200HC-HE	0.41	—	0.48	—	0.55	—	ns
		MachXO2-2000HC-HE	0.42	—	0.49	—	0.56	—	ns
		MachXO2-4000HC-HE	0.43	—	0.50	—	0.58	—	ns
		MachXO2-7000HC-HE	0.46	—	0.54	—	0.62	—	ns
t_{SU_DELPLL}	Clock to Data Setup – PIO Input Register with Data Input Delay	MachXO2-1200HC-HE	2.88	—	3.19	—	3.72	—	ns
		MachXO2-2000HC-HE	2.87	—	3.18	—	3.70	—	ns
		MachXO2-4000HC-HE	2.96	—	3.28	—	3.81	—	ns
		MachXO2-7000HC-HE	3.05	—	3.35	—	3.87	—	ns
t_{H_DELPLL}	Clock to Data Hold – PIO Input Register with Input Data Delay	MachXO2-1200HC-HE	-0.83	—	-0.83	—	-0.83	—	ns
		MachXO2-2000HC-HE	-0.83	—	-0.83	—	-0.83	—	ns
		MachXO2-4000HC-HE	-0.87	—	-0.87	—	-0.87	—	ns
		MachXO2-7000HC-HE	-0.91	—	-0.91	—	-0.91	—	ns
Generic DDRX1 Inputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX1_RX.SCLK.Aligned^{9,12}									
t_{DVA}	Input Data Valid After CLK	All MachXO2 devices, all sides	—	0.317	—	0.344	—	0.368	UI
t_{DVE}	Input Data Hold After CLK		0.742	—	0.702	—	0.668	—	UI
f_{DATA}	DDRX1 Input Data Speed		—	300	—	250	—	208	Mbps
f_{DDRX1}	DDRX1 SCLK Frequency		—	150	—	125	—	104	MHz
Generic DDRX1 Inputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX1_RX.SCLK.Centered^{9,12}									
t_{SU}	Input Data Setup Before CLK	All MachXO2 devices, all sides	0.566	—	0.560	—	0.538	—	ns
t_{HO}	Input Data Hold After CLK		0.778	—	0.879	—	1.090	—	ns
f_{DATA}	DDRX1 Input Data Speed		—	300	—	250	—	208	Mbps
f_{DDRX1}	DDRX1 SCLK Frequency		—	150	—	125	—	104	MHz
Generic DDRX2 Inputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX2_RX.ECLK.Aligned^{9,12}									
t_{DVA}	Input Data Valid After CLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only ¹¹	—	0.316	—	0.342	—	0.364	UI
t_{DVE}	Input Data Hold After CLK		0.710	—	0.675	—	0.679	—	UI
f_{DATA}	DDRX2 Serial Input Data Speed		—	664	—	554	—	462	Mbps
f_{DDRX2}	DDRX2 ECLK Frequency		—	332	—	277	—	231	MHz
f_{SCLK}	SCLK Frequency		—	166	—	139	—	116	MHz
Generic DDRX2 Inputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX2_RX.ECLK.Centered^{9,12}									
t_{SU}	Input Data Setup Before CLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only ¹¹	0.233	—	0.219	—	0.198	—	ns
t_{HO}	Input Data Hold After CLK		0.287	—	0.287	—	0.344	—	ns
f_{DATA}	DDRX2 Serial Input Data Speed		—	664	—	554	—	462	Mbps
f_{DDRX2}	DDRX2 ECLK Frequency		—	332	—	277	—	231	MHz
f_{SCLK}	SCLK Frequency		—	166	—	139	—	116	MHz

Parameter	Description	Device	-6		-5		-4		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Generic DDR4 Inputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX4_RX.ECLK.Aligned^{9, 12}									
t _{DVA}	Input Data Valid After ECLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only. ¹¹	—	0.290	—	0.320	—	0.345	UI
t _{DVE}	Input Data Hold After ECLK		0.739	—	0.699	—	0.703	—	UI
f _{DATA}	DDR4 Serial Input Data Speed		—	756	—	630	—	524	Mbps
f _{DDRX4}	DDR4 ECLK Frequency		—	378	—	315	—	262	MHz
f _{SCLK}	SCLK Frequency		—	95	—	79	—	66	MHz
Generic DDR4 Inputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX4_RX.ECLK.Centered^{9, 12}									
t _{SU}	Input Data Setup Before ECLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only. ¹¹	0.233	—	0.219	—	0.198	—	ns
t _{HO}	Input Data Hold After ECLK		0.287	—	0.287	—	0.344	—	ns
f _{DATA}	DDR4 Serial Input Data Speed		—	756	—	630	—	524	Mbps
f _{DDRX4}	DDR4 ECLK Frequency		—	378	—	315	—	262	MHz
f _{SCLK}	SCLK Frequency		—	95	—	79	—	66	MHz
7:1 LVDS Inputs (GDDR71_RX.ECLK.7:1)^{9, 12}									
t _{DVA}	Input Data Valid After ECLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only. ¹¹	—	0.290	—	0.320	—	0.345	UI
t _{DVE}	Input Data Hold After ECLK		0.739	—	0.699	—	0.703	—	UI
f _{DATA}	DDR71 Serial Input Data Speed		—	756	—	630	—	524	Mbps
f _{DDR71}	DDR71 ECLK Frequency		—	378	—	315	—	262	MHz
f _{CLKIN}	7:1 Input Clock Frequency (SCLK) (minimum limited by PLL)		—	108	—	90	—	75	MHz
Generic DDR Outputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX1_TX.SCLK.Aligned^{9, 12}									
t _{DIA}	Output Data Invalid After CLK Output	All MachXO2 devices, all sides.	—	0.520	—	0.550	—	0.580	ns
t _{DIB}	Output Data Invalid Before CLK Output		—	0.520	—	0.550	—	0.580	ns
f _{DATA}	DDRX1 Output Data Speed		—	300	—	250	—	208	Mbps
f _{DDRX1}	DDRX1 SCLK frequency		—	150	—	125	—	104	MHz
Generic DDR Outputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX1_TX.SCLK.Centered^{9, 12}									
t _{DVB}	Output Data Valid Before CLK Output	All MachXO2 devices, all sides.	1.210	—	1.510	—	1.870	—	ns
t _{DVA}	Output Data Valid After CLK Output		1.210	—	1.510	—	1.870	—	ns
f _{DATA}	DDRX1 Output Data Speed		—	300	—	250	—	208	Mbps
f _{DDRX1}	DDRX1 SCLK Frequency (minimum limited by PLL)		—	150	—	125	—	104	MHz
Generic DDRX2 Outputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX2_TX.ECLK.Aligned^{9, 12}									
t _{DIA}	Output Data Invalid After CLK Output	MachXO2-640U, MachXO2-1200/U and larger devices, top side only.	—	0.200	—	0.215	—	0.230	ns
t _{DIB}	Output Data Invalid Before CLK Output		—	0.200	—	0.215	—	0.230	ns
f _{DATA}	DDRX2 Serial Output Data Speed		—	664	—	554	—	462	Mbps
f _{DDRX2}	DDRX2 ECLK frequency		—	332	—	277	—	231	MHz
f _{SCLK}	SCLK Frequency		—	166	—	139	—	116	MHz

Parameter	Description	Device	-3		-2		-1		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{SU_DEL}	Clock to Data Setup – PIO Input Register with Data Input Delay	MachXO2-256ZE	2.62	—	2.91	—	3.14	—	ns
		MachXO2-640ZE	2.56	—	2.85	—	3.08	—	ns
		MachXO2-1200ZE	2.30	—	2.57	—	2.79	—	ns
		MachXO2-2000ZE	2.25	—	2.50	—	2.70	—	ns
		MachXO2-4000ZE	2.39	—	2.60	—	2.76	—	ns
		MachXO2-7000ZE	2.17	—	2.33	—	2.43	—	ns
t_{H_DEL}	Clock to Data Hold – PIO Input Register with Input Data Delay	MachXO2-256ZE	-0.44	—	-0.44	—	-0.44	—	ns
		MachXO2-640ZE	-0.43	—	-0.43	—	-0.43	—	ns
		MachXO2-1200ZE	-0.28	—	-0.28	—	-0.28	—	ns
		MachXO2-2000ZE	-0.31	—	-0.31	—	-0.31	—	ns
		MachXO2-4000ZE	-0.34	—	-0.34	—	-0.34	—	ns
		MachXO2-7000ZE	-0.21	—	-0.21	—	-0.21	—	ns
f_{MAX_IO}	Clock Frequency of I/O and PFU Register	All MachXO2 devices	—	150	—	125	—	104	MHz

General I/O Pin Parameters (Using Edge Clock without PLL)

t_{COE}	Clock to Output – PIO Output Register	MachXO2-1200ZE	—	11.10	—	11.51	—	11.91	ns
		MachXO2-2000ZE	—	11.10	—	11.51	—	11.91	ns
		MachXO2-4000ZE	—	10.89	—	11.28	—	11.67	ns
		MachXO2-7000ZE	—	11.10	—	11.51	—	11.91	ns
t_{SUE}	Clock to Data Setup – PIO Input Register	MachXO2-1200ZE	-0.23	—	-0.23	—	-0.23	—	ns
		MachXO2-2000ZE	-0.23	—	-0.23	—	-0.23	—	ns
		MachXO2-4000ZE	-0.15	—	-0.15	—	-0.15	—	ns
		MachXO2-7000ZE	-0.23	—	-0.23	—	-0.23	—	ns
t_{HE}	Clock to Data Hold – PIO Input Register	MachXO2-1200ZE	3.81	—	4.11	—	4.52	—	ns
		MachXO2-2000ZE	3.81	—	4.11	—	4.52	—	ns
		MachXO2-4000ZE	3.60	—	3.89	—	4.28	—	ns
		MachXO2-7000ZE	3.81	—	4.11	—	4.52	—	ns
t_{SU_DELE}	Clock to Data Setup – PIO Input Register with Data Input Delay	MachXO2-1200ZE	2.78	—	3.11	—	3.40	—	ns
		MachXO2-2000ZE	2.78	—	3.11	—	3.40	—	ns
		MachXO2-4000ZE	3.11	—	3.48	—	3.79	—	ns
		MachXO2-7000ZE	2.94	—	3.30	—	3.60	—	ns
t_{H_DELE}	Clock to Data Hold – PIO Input Register with Input Data Delay	MachXO2-1200ZE	-0.29	—	-0.29	—	-0.29	—	ns
		MachXO2-2000ZE	-0.29	—	-0.29	—	-0.29	—	ns
		MachXO2-4000ZE	-0.46	—	-0.46	—	-0.46	—	ns
		MachXO2-7000ZE	-0.37	—	-0.37	—	-0.37	—	ns

General I/O Pin Parameters (Using Primary Clock with PLL)

t_{COPLL}	Clock to Output – PIO Output Register	MachXO2-1200ZE	—	7.95	—	8.07	—	8.19	ns
		MachXO2-2000ZE	—	7.97	—	8.10	—	8.22	ns
		MachXO2-4000ZE	—	7.98	—	8.10	—	8.23	ns
		MachXO2-7000ZE	—	8.02	—	8.14	—	8.26	ns
t_{SUPLL}	Clock to Data Setup – PIO Input Register	MachXO2-1200ZE	0.85	—	0.85	—	0.89	—	ns
		MachXO2-2000ZE	0.84	—	0.84	—	0.86	—	ns
		MachXO2-4000ZE	0.84	—	0.84	—	0.85	—	ns
		MachXO2-7000ZE	0.83	—	0.83	—	0.81	—	ns

Flash Download Time^{1,2}

Symbol	Parameter	Device	Typ.	Units
$t_{REFRESH}$	POR to Device I/O Active	LCMXO2-256	0.6	ms
		LCMXO2-640	1.0	ms
		LCMXO2-640U	1.9	ms
		LCMXO2-1200	1.9	ms
		LCMXO2-1200U	1.4	ms
		LCMXO2-2000	1.4	ms
		LCMXO2-2000U	2.4	ms
		LCMXO2-4000	2.4	ms
		LCMXO2-7000	3.8	ms

1. Assumes sysMEM EBR initialized to an all zero pattern if they are used.

2. The Flash download time is measured starting from the maximum voltage of POR trip point.

JTAG Port Timing Specifications

Symbol	Parameter	Min.	Max.	Units
f_{MAX}	TCK clock frequency	—	25	MHz
t_{BTCPH}	TCK [BSCAN] clock pulse width high	20	—	ns
t_{BTCPL}	TCK [BSCAN] clock pulse width low	20	—	ns
t_{BTS}	TCK [BSCAN] setup time	10	—	ns
t_{BTH}	TCK [BSCAN] hold time	8	—	ns
t_{BTCO}	TAP controller falling edge of clock to valid output	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to valid disable	—	10	ns
t_{BTOEN}	TAP controller falling edge of clock to valid enable	—	10	ns
t_{BTCRS}	BSCAN test capture register setup time	8	—	ns
t_{BTCRH}	BSCAN test capture register hold time	20	—	ns
t_{BUTCO}	BSCAN test update register, falling edge of clock to valid output	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to valid disable	—	25	ns
$t_{BTUOPEN}$	BSCAN test update register, falling edge of clock to valid enable	—	25	ns

	MachXO2-1200					MachXO2-1200U
	100 TQFP	132 csBGA	144 TQFP	25 WLCSP	32 QFN ¹	256 ftBGA
General Purpose I/O per Bank						
Bank 0	18	25	27	11	9	50
Bank 1	21	26	26	0	2	52
Bank 2	20	28	28	7	9	52
Bank 3	20	25	26	0	2	16
Bank 4	0	0	0	0	0	16
Bank 5	0	0	0	0	0	20
Total General Purpose Single Ended I/O	79	104	107	18	22	206
Differential I/O per Bank						
Bank 0	9	13	14	5	4	25
Bank 1	10	13	13	0	1	26
Bank 2	10	14	14	2	4	26
Bank 3	10	12	13	0	1	8
Bank 4	0	0	0	0	0	8
Bank 5	0	0	0	0	0	10
Total General Purpose Differential I/O	39	52	54	7	10	103
Dual Function I/O	31	33	33	18	22	33
High-speed Differential I/O						
Bank 0	4	7	7	0	0	14
Gearboxes						
Number of 7:1 or 8:1 Output Gearbox Available (Bank 0)	4	7	7	0	0	14
Number of 7:1 or 8:1 Input Gearbox Available (Bank 2)	5	7	7	0	2	14
DQS Groups						
Bank 1	1	2	2	0	0	2
VCCIO Pins						
Bank 0	2	3	3	1	2	4
Bank 1	2	3	3	0	1	4
Bank 2	2	3	3	1	2	4
Bank 3	3	3	3	0	1	1
Bank 4	0	0	0	0	0	2
Bank 5	0	0	0	0	0	1
VCC	2	4	4	2	2	8
GND	8	10	12	2	2	24
NC	1	1	8	0	0	1
Reserved for Configuration	1	1	1	1	1	1
Total Count of Bonded Pins	100	132	144	25	32	256

1. Lattice recommends soldering the central thermal pad onto the top PCB ground for improved thermal resistance.

	MachXO2-7000					
	144 TQFP	256 caBGA	256 ftBGA	332 caBGA	400 caBGA	484 fpBGA
General Purpose I/O per Bank						
Bank 0	27	50	50	68	83	82
Bank 1	29	52	52	70	84	84
Bank 2	29	52	52	70	84	84
Bank 3	9	16	16	24	28	28
Bank 4	10	16	16	16	24	24
Bank 5	10	20	20	30	32	32
Total General Purpose Single Ended I/O	114	206	206	278	335	334
Differential I/O per Bank						
Bank 0	14	25	25	34	42	41
Bank 1	14	26	26	35	42	42
Bank 2	14	26	26	35	42	42
Bank 3	4	8	8	12	14	14
Bank 4	5	8	8	8	12	12
Bank 5	5	10	10	15	16	16
Total General Purpose Differential I/O	56	103	103	139	168	167
Dual Function I/O	37	37	37	37	37	37
High-speed Differential I/O						
Bank 0	9	20	20	21	21	21
Gearboxes						
Number of 7:1 or 8:1 Output Gearbox Available (Bank 0)	9	20	20	21	21	21
Number of 7:1 or 8:1 Input Gearbox Available (Bank 2)	14	20	20	21	21	21
DQS Groups						
Bank 1	2	2	2	2	2	2
VCCIO Pins						
Bank 0	3	4	4	4	5	10
Bank 1	3	4	4	4	5	10
Bank 2	3	4	4	4	5	10
Bank 3	1	1	1	2	2	3
Bank 4	1	2	2	1	2	4
Bank 5	1	1	1	2	2	3
VCC	4	8	8	8	10	12
GND	12	24	24	27	33	48
NC	1	1	1	1	0	49
Reserved for Configuration	1	1	1	1	1	1
Total Count of Bonded Pins	144	256	256	332	400	484

Ordering Information

MachXO2 devices have top-side markings, for commercial and industrial grades, as shown below:



Notes:

1. *Markings are abbreviated for small packages.*
2. See [PCN 05A-12](#) for information regarding a change to the top-side mark logo.

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMxo2-2000ZE-1TG100C	2112	1.2 V	-1	Halogen-Free TQFP	100	COM
LCMxo2-2000ZE-2TG100C	2112	1.2 V	-2	Halogen-Free TQFP	100	COM
LCMxo2-2000ZE-3TG100C	2112	1.2 V	-3	Halogen-Free TQFP	100	COM
LCMxo2-2000ZE-1MG132C	2112	1.2 V	-1	Halogen-Free csBGA	132	COM
LCMxo2-2000ZE-2MG132C	2112	1.2 V	-2	Halogen-Free csBGA	132	COM
LCMxo2-2000ZE-3MG132C	2112	1.2 V	-3	Halogen-Free csBGA	132	COM
LCMxo2-2000ZE-1TG144C	2112	1.2 V	-1	Halogen-Free TQFP	144	COM
LCMxo2-2000ZE-2TG144C	2112	1.2 V	-2	Halogen-Free TQFP	144	COM
LCMxo2-2000ZE-3TG144C	2112	1.2 V	-3	Halogen-Free TQFP	144	COM
LCMxo2-2000ZE-1BG256C	2112	1.2 V	-1	Halogen-Free caBGA	256	COM
LCMxo2-2000ZE-2BG256C	2112	1.2 V	-2	Halogen-Free caBGA	256	COM
LCMxo2-2000ZE-3BG256C	2112	1.2 V	-3	Halogen-Free caBGA	256	COM
LCMxo2-2000ZE-1FTG256C	2112	1.2 V	-1	Halogen-Free ftBGA	256	COM
LCMxo2-2000ZE-2FTG256C	2112	1.2 V	-2	Halogen-Free ftBGA	256	COM
LCMxo2-2000ZE-3FTG256C	2112	1.2 V	-3	Halogen-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMxo2-4000ZE-1QN84C	4320	1.2 V	-1	Halogen-Free QFN	84	COM
LCMxo2-4000ZE-2QN84C	4320	1.2 V	-2	Halogen-Free QFN	84	COM
LCMxo2-4000ZE-3QN84C	4320	1.2 V	-3	Halogen-Free QFN	84	COM
LCMxo2-4000ZE-1MG132C	4320	1.2 V	-1	Halogen-Free csBGA	132	COM
LCMxo2-4000ZE-2MG132C	4320	1.2 V	-2	Halogen-Free csBGA	132	COM
LCMxo2-4000ZE-3MG132C	4320	1.2 V	-3	Halogen-Free csBGA	132	COM
LCMxo2-4000ZE-1TG144C	4320	1.2 V	-1	Halogen-Free TQFP	144	COM
LCMxo2-4000ZE-2TG144C	4320	1.2 V	-2	Halogen-Free TQFP	144	COM
LCMxo2-4000ZE-3TG144C	4320	1.2 V	-3	Halogen-Free TQFP	144	COM
LCMxo2-4000ZE-1BG256C	4320	1.2 V	-1	Halogen-Free caBGA	256	COM
LCMxo2-4000ZE-2BG256C	4320	1.2 V	-2	Halogen-Free caBGA	256	COM
LCMxo2-4000ZE-3BG256C	4320	1.2 V	-3	Halogen-Free caBGA	256	COM
LCMxo2-4000ZE-1FTG256C	4320	1.2 V	-1	Halogen-Free ftBGA	256	COM
LCMxo2-4000ZE-2FTG256C	4320	1.2 V	-2	Halogen-Free ftBGA	256	COM
LCMxo2-4000ZE-3FTG256C	4320	1.2 V	-3	Halogen-Free ftBGA	256	COM
LCMxo2-4000ZE-1BG332C	4320	1.2 V	-1	Halogen-Free caBGA	332	COM
LCMxo2-4000ZE-2BG332C	4320	1.2 V	-2	Halogen-Free caBGA	332	COM
LCMxo2-4000ZE-3BG332C	4320	1.2 V	-3	Halogen-Free caBGA	332	COM
LCMxo2-4000ZE-1FG484C	4320	1.2 V	-1	Halogen-Free fpBGA	484	COM
LCMxo2-4000ZE-2FG484C	4320	1.2 V	-2	Halogen-Free fpBGA	484	COM
LCMxo2-4000ZE-3FG484C	4320	1.2 V	-3	Halogen-Free fpBGA	484	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMxo2-1200HC-4SG32I	1280	2.5 V / 3.3 V	-4	Halogen-Free QFN	32	IND
LCMxo2-1200HC-5SG32I	1280	2.5 V / 3.3 V	-5	Halogen-Free QFN	32	IND
LCMxo2-1200HC-6SG32I	1280	2.5 V / 3.3 V	-6	Halogen-Free QFN	32	IND
LCMxo2-1200HC-4TG100I	1280	2.5 V / 3.3 V	-4	Halogen-Free TQFP	100	IND
LCMxo2-1200HC-5TG100I	1280	2.5 V / 3.3 V	-5	Halogen-Free TQFP	100	IND
LCMxo2-1200HC-6TG100I	1280	2.5 V / 3.3 V	-6	Halogen-Free TQFP	100	IND
LCMxo2-1200HC-4MG132I	1280	2.5 V / 3.3 V	-4	Halogen-Free csBGA	132	IND
LCMxo2-1200HC-5MG132I	1280	2.5 V / 3.3 V	-5	Halogen-Free csBGA	132	IND
LCMxo2-1200HC-6MG132I	1280	2.5 V / 3.3 V	-6	Halogen-Free csBGA	132	IND
LCMxo2-1200HC-4TG144I	1280	2.5 V / 3.3 V	-4	Halogen-Free TQFP	144	IND
LCMxo2-1200HC-5TG144I	1280	2.5 V / 3.3 V	-5	Halogen-Free TQFP	144	IND
LCMxo2-1200HC-6TG144I	1280	2.5 V / 3.3 V	-6	Halogen-Free TQFP	144	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMxo2-1200UHC-4FTG256I	1280	2.5 V / 3.3 V	-4	Halogen-Free ftBGA	256	IND
LCMxo2-1200UHC-5FTG256I	1280	2.5 V / 3.3 V	-5	Halogen-Free ftBGA	256	IND
LCMxo2-1200UHC-6FTG256I	1280	2.5 V / 3.3 V	-6	Halogen-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMxo2-2000HC-4TG100I	2112	2.5 V / 3.3 V	-4	Halogen-Free TQFP	100	IND
LCMxo2-2000HC-5TG100I	2112	2.5 V / 3.3 V	-5	Halogen-Free TQFP	100	IND
LCMxo2-2000HC-6TG100I	2112	2.5 V / 3.3 V	-6	Halogen-Free TQFP	100	IND
LCMxo2-2000HC-4MG132I	2112	2.5 V / 3.3 V	-4	Halogen-Free csBGA	132	IND
LCMxo2-2000HC-5MG132I	2112	2.5 V / 3.3 V	-5	Halogen-Free csBGA	132	IND
LCMxo2-2000HC-6MG132I	2112	2.5 V / 3.3 V	-6	Halogen-Free csBGA	132	IND
LCMxo2-2000HC-4TG144I	2112	2.5 V / 3.3 V	-4	Halogen-Free TQFP	144	IND
LCMxo2-2000HC-5TG144I	2112	2.5 V / 3.3 V	-5	Halogen-Free TQFP	144	IND
LCMxo2-2000HC-6TG144I	2112	2.5 V / 3.3 V	-6	Halogen-Free TQFP	144	IND
LCMxo2-2000HC-4BG256I	2112	2.5 V / 3.3 V	-4	Halogen-Free caBGA	256	IND
LCMxo2-2000HC-5BG256I	2112	2.5 V / 3.3 V	-5	Halogen-Free caBGA	256	IND
LCMxo2-2000HC-6BG256I	2112	2.5 V / 3.3 V	-6	Halogen-Free caBGA	256	IND
LCMxo2-2000HC-4FTG256I	2112	2.5 V / 3.3 V	-4	Halogen-Free ftBGA	256	IND
LCMxo2-2000HC-5FTG256I	2112	2.5 V / 3.3 V	-5	Halogen-Free ftBGA	256	IND
LCMxo2-2000HC-6FTG256I	2112	2.5 V / 3.3 V	-6	Halogen-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMxo2-2000UHC-4FG484I	2112	2.5 V / 3.3 V	-4	Halogen-Free fpBGA	484	IND
LCMxo2-2000UHC-5FG484I	2112	2.5 V / 3.3 V	-5	Halogen-Free fpBGA	484	IND
LCMxo2-2000UHC-6FG484I	2112	2.5 V / 3.3 V	-6	Halogen-Free fpBGA	484	IND